



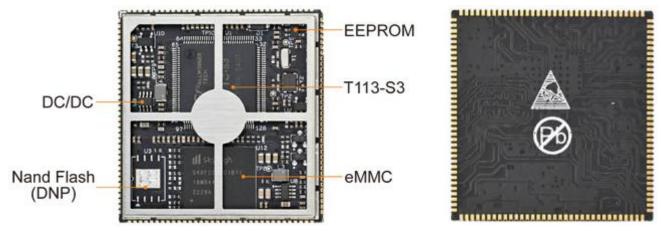
MYC-YT113X System-On-Module Overview



- ✓ Up to 1.2GHz Allwinner T113-S3 Dual-core ARM Cortex-A7 MPU with 128MB DDR3 and Single-core HiFi4 DSP
- ✓ 4GB eMMC/256MB Nand Flash, 32KB EEPROM
- ✓ 1.0mm pitch 140-pin Stamp Hole Expansion Interface
- ✓ Supports Running Linux 5.4 OS

MYIR Make Your Idea Real

Measuring only 37mm by 39mm, the MYC-YT113X is a low-cost embedded ARM System-On-Module (SoM) based on **Allwinner T113-S3** processor which features up to **1.2GHz Dual-core ARM Cortex-A7** MPU with built-in 128MB DDR3, single-core HiFi4 DSP, Robust Video Engine and a broad range of peripherals like Gigabit Ethernet, 2 x CAN, 2 x USB2.0, 6 x UART, etc. The MYC-YT113X takes full features of the T113-S3 processor and has standard configurations for 256MB Nand Flash or 4GB eMMC external memory options. A number of peripheral and IO signals are access through 1.0mm pitch 140-pin stamp-hole (Castellated-Hole) expansion interface. It is capable of running Linux and suitable for applications such as HMI, industrial automation, display and control terminals.

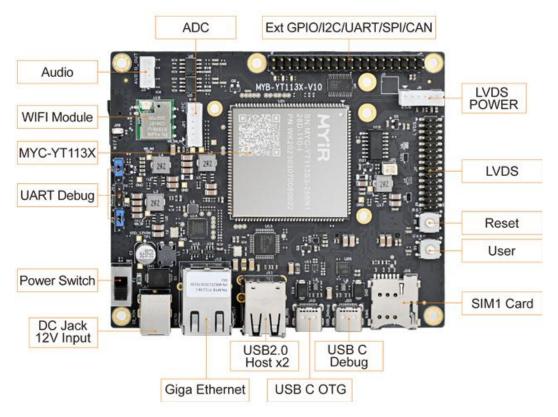


MYC-YT113X SOM (Top-view and Bottom-view)

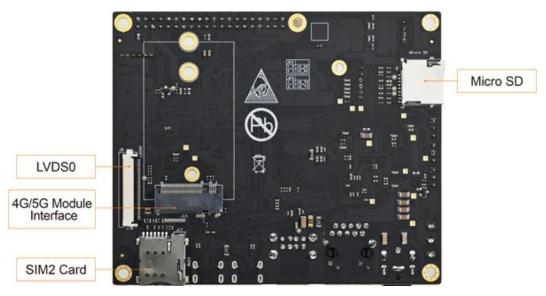


MYC-YT113X Function Block Diagram

MYIR provides MYD-YT113X Development Board for evaluating the MYC-YT113X System-On-Module. It takes full advantages of the Allwinner T113-S3 MPU to explore a rich set of peripherals and interfaces to the base board including serial ports, one Gigabit Ethernet, two USB 2.0 HOST and one USB 2.0 OTG, one Micro SD card slot, one M.2 Socket for USB based 4G/5G LTE Module with two SIM card holders, one USB2.0 based WiFi module, one GPIO/I2C/UART/SPI/CAN extension header, Audio input/output and LVDS display interface.



MYD-YT113X Development Board Top-view



MYD-YT113X Development Board Bottom-view

MYIR also offers MY-WIREDCOM RPI Module (RS232/RS485/CAN) and MY-LVDS070C LCD Module as options for the MYD-YT113X Development Board to enhance the functionality of the board.



The MYC-YT113X Module is using 14 x 14 mm, eLQFP128 package Allwinner T113-S3 processor which is designed for the automotive and industrial control products. It integrates dual-core Cortex-A7 CPU and single-core HiFi4 DSP to provide the high efficient computing power. T113-S3 supports full format decoding such as H.265, H.264, MPEG-1/2/4, JPEG, VC1, and so on. The independent hardware encoder can encode in JPEG or MJPEG. Integrated multi ADCs/DACs and I2S/PCM/DMIC/OWA audio interfaces can provide the perfect voice interaction solution. T113-S3 comes with extensive connectivity to facilitate product expansion, such as CAN, USB, SDIO, EMAC, TWI, UART, SPI, PWM, GPADC, IR TX&RX, and so on.

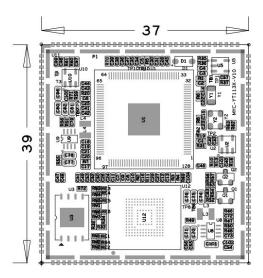
Features	Description		
СРИ	Dual-core ARM Cortex-A7		
	• 32KB L1 I-cache + 32KB L1 D-cache per core, and 256KB L2 cache		
DSP	• Single-core HiFi4		
	• 32KB I-cache + 32KB D-cache		
Memory	• SIP 128MB DDR3		
метногу	• SD 3.0/eMMC 5.1, SPI Nor/NAND Flash		
	Video decoding		
	• H.265 up to 1080p@60fps		
	• H.264 up to 1080p@60fps		
Video Engine	● H.263, MPEG-1/2/4, JPEG, Xvid, Sorenson Spark, up to 1080p@60fps		
	Video encoding		
	• JPEG/MJPEG up to 1080p@60fps		
	• Supports input picture scaler up/down		
	• Allwinner SmartColor2.0 post processing for an excellent display experience		
Display Engine	• Supports de-interlace (DI) up to 1080p@60fps		
	• Supports G2D hardware accelerator including rotate, mixer, lbc decompression		
	• CVBS OUT interface, supporting NTSC and PAL format		
	• RGB LCD output interface up to 1920 x 1080@60fps		
Video OUT	• Dual link LVDS interface up to 1920 x 1080@60fps		
	• 4-lane MIPI DSI interface up to 1920 x 1080@60fps		
	• 8-bit parallel CSI interface		
Video IN	• CVBS IN interface, supporting NTSC and PAL format		
	• 2 DACs and 3 ADCs		
Audio	• Analog audio interfaces: MICIN3P/N,LINEINL/R, FMINL/R,HPOUTL/R		
	 Digital audio interfaces: 12S/PCM, DMIC, OWA 		
	• AES, DES, 3DES encryption and decryption algorithms		
	 RSA signature verification algorithm 		
Security System	• MD5/SHA and HMAC tamper proofing		
	 Hardware random number generator 		
	 Integrated 2Kbits OTP storage space 		
	 USB2.0 0TG,USB2.0 Host 		
	• SDIO 3.0 ,SPI x 2,UART x 6, TWI x 4, CAN x 2		
Connectivity	 PWM (8-ch),GPADC(1-ch),TPADC(4-ch),IR TX&RX 		
	 10/100/1000M EMAC with RMII and RGMII interfaces 		
Package	 eOFP128, 14 mm x 14 mm 		
i uchuge	Features of T113-S3 Processor		

Features of T113-S3 Processor

MYIR Make Your Idea Real

Video Input	ARM Cortex-A7 x2	HiFi4 DSP	Connectivity
CVBS IN	I cache 32KB 32KB L2 cache	l-cache 32 KB D-cache 32 KB	USB2.0 DRD
Parallel CSI	NEON Thumb-2 256 KB	I-ram 64 KB D-ram 64 KB	USB2.0 HOST
Video Output	Display Engine	Internal System	SD103.0
video output		ССО	SPIx2
MIPI DSI	DE	GIC	(Supports SPI Nand/Nor Flash)
RGB	DI	DMA	TWI x 4
RGB	G2D	Thermal Sensor	UART x 6
Dual link LVDS		Timer	100M/1000M EMAC
CVBS OUT	Video Engine		100M/1000M EMAC
	Video Decoding	High Speed Timer	GPADC(1-ch)
Audio	H.265/H.264	IOMMU	TPADC(4-ch)
Addio	Video Encoding JPEG/MJPEG	Security System	0
Audio Codec	JFEG/MJFEG	Crypto Engine	PWM(8-ch)
I2S/PCM x2	Memory		LEDC
*	SIP 128 MB DDR3	Security ID	
DMIC		TrustZone	IR TX
OWA IN/OUT	SD3.0/eMMC5.0	Secure Boot	IR RX

Allwinner T113-S3 Block Diagram



MYC-YT113X Dimensions Chart (Unit: mm)

The MYC-YT113X System-On-Module takes full features of T113-S3 processor and the main features are characterized as below:

Mechanical Parameters

- Dimensions: 37mm x 39mm
- PCB Layers: 6-layer design
- Power supply: +5V/1A
- Working temperature: -40~85 Celsius (industrial grade)

Processor

- Allwinner T113-S3 processor
 - Up to 1.2GHz Dual-core Arm Cortex-A7 with built-in 128MB DDR3
 - Single-core HiFi4 DSP
 - Supports H.265/H.264 video decoding up to 1080p@60fps and JPEG/MJPEG video encoding up to 1080p@60fps

External Memory

- 4GB eMMC or 256MB Nand FLASH
- 32KB EEPROM

Peripherals and Signals Routed to Pins

- 1.0mm pitch 140-pin Stamp Hole Expansion Interface
 - 1 x RGMII/RMII
 - 2 x USB2.0
 - 6 x UART
 - 2 x CAN
 - 4 x TWI
 - 2 x SPI
 - 1 x GPADC and 4 x TPADC
 - 1 x MIPI DSI
 - 2 x LVDS
 - 1x RGB
 - 1 x CVBS Out (TV Out)
 - 1 x Parallel CSI
 - 2 x CVBS In (TV In)
 - 2 x I2S
 - Up to 59 GPIOs

Note: the peripheral signals brought out to the expansion interface are listed in maximum number. Some signals are reused. Please refer to the processor datasheet and the SOM pinout description file.

Software Features

The MYC-YT113X System-On-Module supports Linux OS and comes with complete software package. The kernel and many peripheral drivers are available in source code to assist clients to expedite their development. The following are a summary of the software features:

Item	Feature	Description	Source Code
Bootloader	U-boot	Boot boot program uboot_2018.05	YES
Linux kernel	Linux kernel	Customized base on official kernel_5.4.61 version	YES
	USB Host	USB Host driver	YES
	USB OTG	USB OTG driver	YES
	I2C	I2C bus driver	YES
	SPI	SPI bus driver	YES
	Ethernet	YT8531SH driver	YES
	SDHI	EMMC/SD card storage driver	YES
	LVDS	LCD driver	YES
D · · · ·	Touch	Touch screen driver	YES
	Audio	SPDIF driver	YES
Device driver	Watchdog	Watchdog driver	YES
	4G/5G	4G/5G driver	YES
	PWM	PWM control driver	YES
	ADC	ADC driver	YES
	RTC	RTC driver	YES
	GPIO	Universal GPIO driver	YES
	UART	RS232/RS485/TTL driver	YES
	CAN	CAN driver	YES
	WIFI	RTL8731BU driver	YES
	t113_linux_myir_emmc_core	Image built with Buildroot, excluding GUI interface	YES
File system	t113_linux_myir_emmc_full	A fully functional image built with Buildroot	YES
ine system	t113_linux_myir_nand	Image built with Buildroot, excluding GUI interface, used for Nand Flash version	YES

MYC-YT113X Software Features

Order Information

Product Item	Part No.	Packing List	
MYC-YT113X System-On-Module	MYC-YT113S3-256N128D-110-I	✓ One MYC-YT113X System-On-Module	
	MYC-YT113S3-4E128D-110-I-G		
MYD-YT113X Development Board	MYD-YT113S3-256N128D-110-I	 ✓ One MYD-YT113X Development Board (including MYC-YT113X SOM) ✓ One USB to UART Debug cable 	
	MYD-YT113S3-4E128D-110-I-G	 ✓ One 12V/2A Power adapter ✓ One DC Power jack adapter ✓ One Quick Start Guide 	
MY-LVDS070C 7-inch LCD Module	MY-LVDS070C	Add-on Options MY-LVDS070C 7-inch LCD Module MY-WIREDCOM Module	
MY-WIREDCOM RPI Module	MY-WIREDCOM		
Note:		,	

1. One MYD-YT113X Development Board includes one System-On-Module MYC-YT113X mounted on the base board. If you need more SOMs, you can order extra ones.

2. Discounts are available for bulk orders.

3. We provide OEM/ODM services to reduce time and save cost for customers.



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